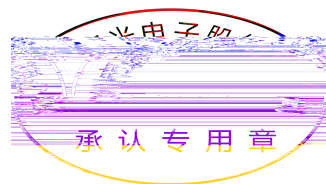
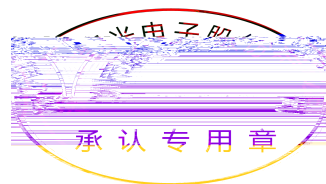
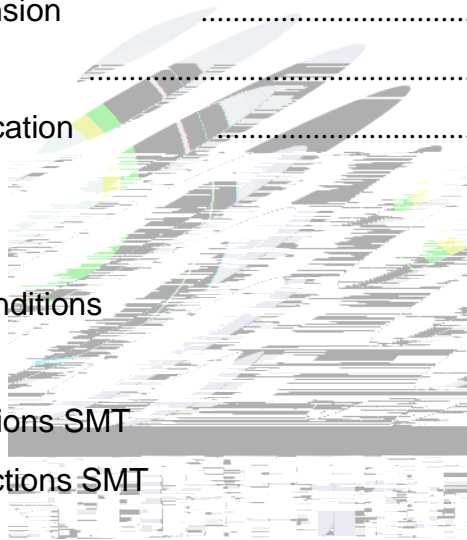


SPECIFICATION



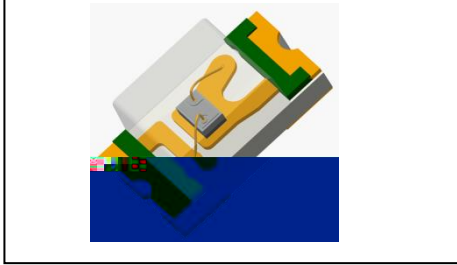
Contents

- 1. Description
 - 1.1 General Description
 - 1.2 Features
 - 1.3 Application
 - 1.4 Package Dimension
 - 1.5 Product Parameters
 - 1.6 Typical Optical Characteristics Curves
- 2. Packaging
 - 2.1 Packaging Specification
 - 2.1.1 Carrier Tape Dimension 11
 - 2.1.2 Reel Dimension 11
 - 2.1.3 Label Form Specification 11
 - 2.2 Moisture Resistant Packing
 - 2.3 Cardboard Box
 - 2.4 Reliability Test Items And Conditions
 - 2.5 Criteria For Judging Damage
- 3. SMT Reflow Soldering Instructions SMT
 - 3.1 SMT Reflow Soldering Instructions SMT
- 4. Handling Precautions
 - 4.1 Handling Precautions



1. Description

1.1 General Description



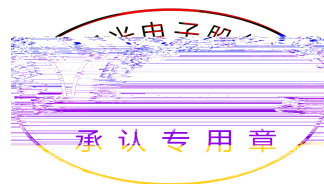
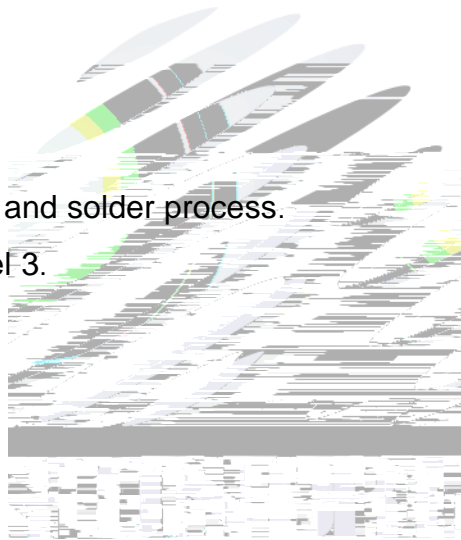
The Colour LED which was fabricated using a green chip Package Dimension :
1.6mmX0.8mmX0.7mm.

1.2 Features

- Extremely wide viewing angle.
- Suitable for all SMT assembly and solder process.
- Moisture sensitivity level: Level 3.
- RoHS compliant.

1.3 Application

- Optical indicator.
- Switch and symbol, display.
- General use.



1.4 Package Dimension

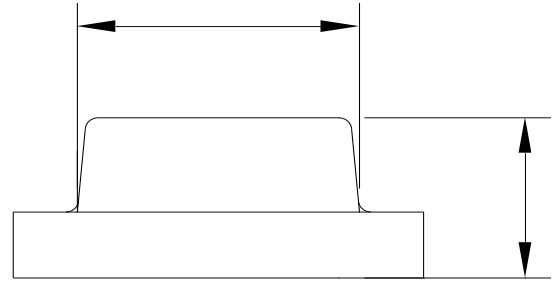


Fig.1-2 Side view

Fig.1-1 Top view

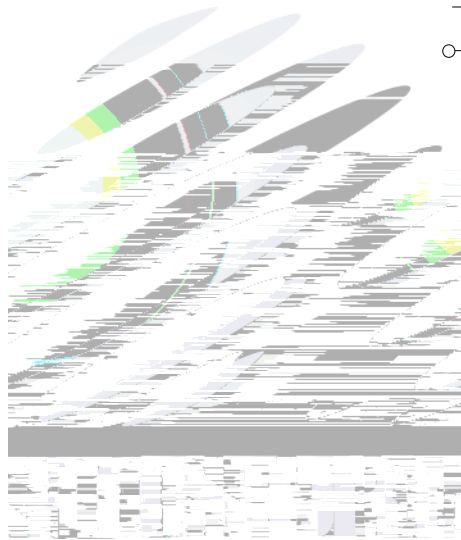


Fig.1-3 Bottom view

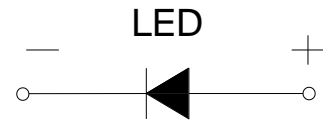


Fig.1-4 Polarity

Fig.1-5 Soldering patterns

Notes

All dimensions units are millimeters.

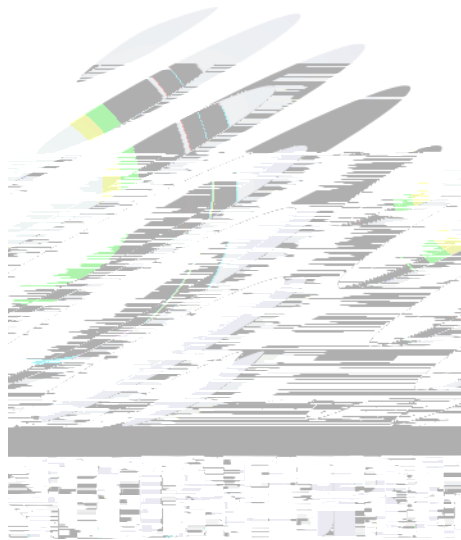
All dimensions tolerances are 0.2mm unless otherwise noted.

1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

| Item | Test Condition | Symbol | Value | | | Unit |
|-------------------------|---------------------|--------|-------------|------|------|------|
| | | | Min. () | Typ. | Max. | |
| Spectral Half Bandwidth | I _F =5mA | | -- | 30 | -- | nm |
| Forward Voltage | I _F =5mA | F0 | 2.6 | -- | 2.8 | V |
| | | | 2.8 | -- | 3.0 | V |
| | | H0 | 3.0 | -- | 3.2 | V |

I_O



Notes : V_R=5V For test conditions. V_R=5V

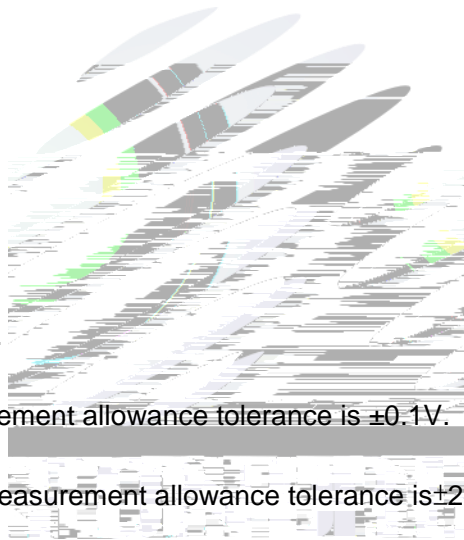
83reW* n93/P A/CID 34/Lang (en-US)9BDC q46.56 635.14 126.62 64[83reW* n93/P A/CID 34/.58 606.58 Tm8.2516

Table 1-2 Absolute Maximum Ratings at Ts=25°C

| Parameter | Symbol | Rating | Units |
|-------------------|--------|--------|-------|
| Power Dissipation | P_d | 68 | mW |

Notes

1. 1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$.
3. The above dominant wavelength measurement allowance tolerance is $\pm 2nm$.
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate



1.6 Typical Optical Characteristics Curves

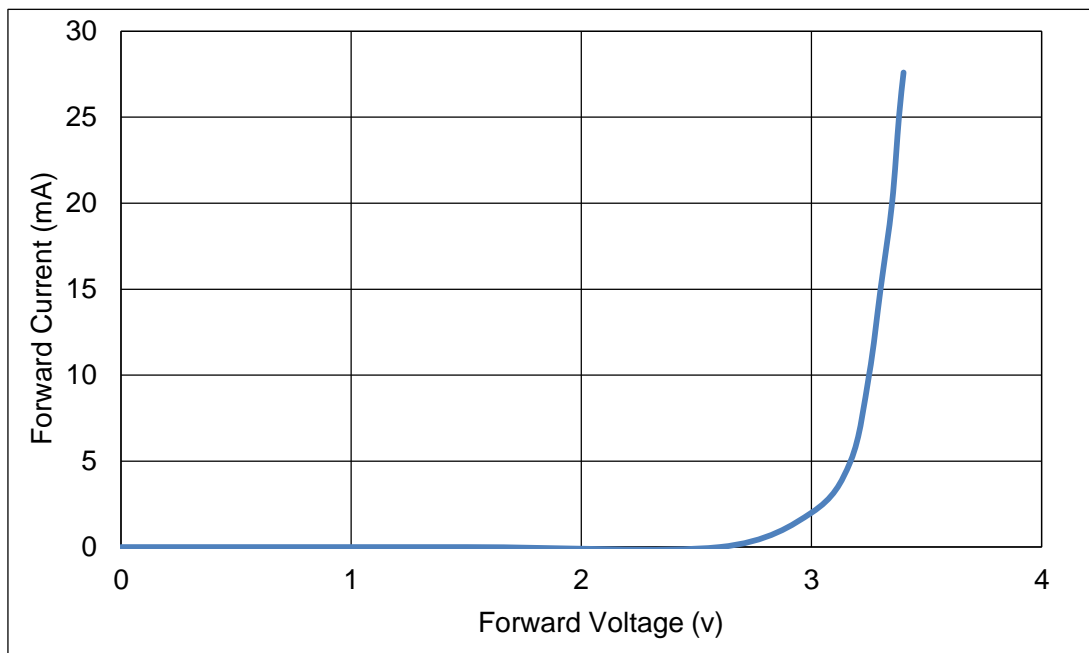
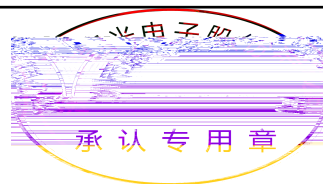


Fig 1-6 Forward Voltage Vs. Forward Current



Fig 1-7 Forward Current Vs. Relative Intensity



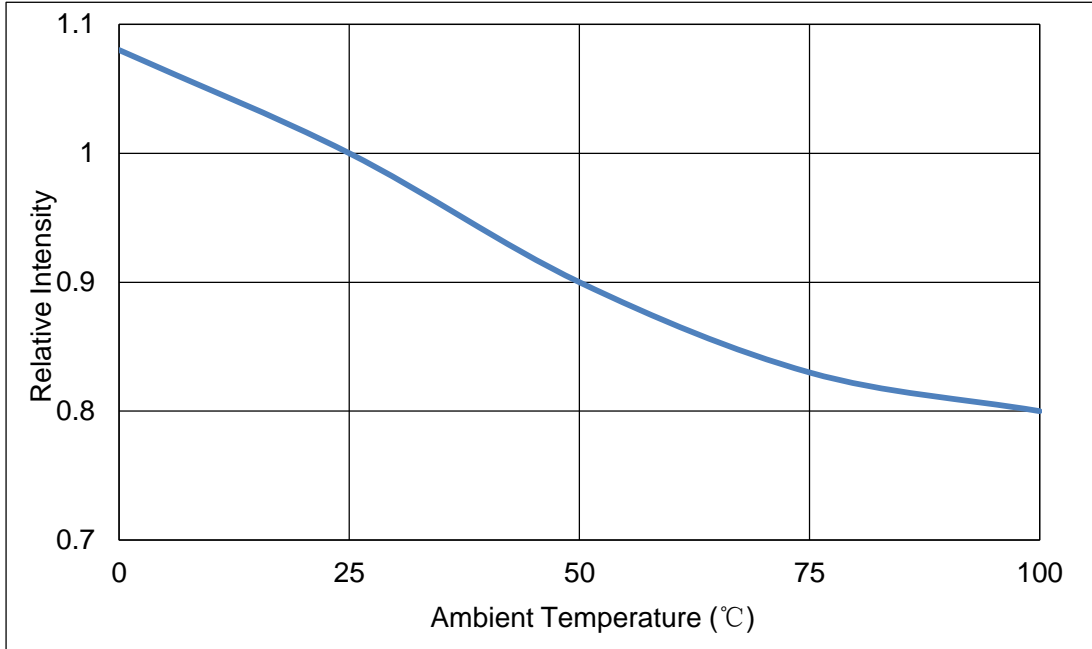


Fig 1-8 Pin Temperature Vs Relative Intensity

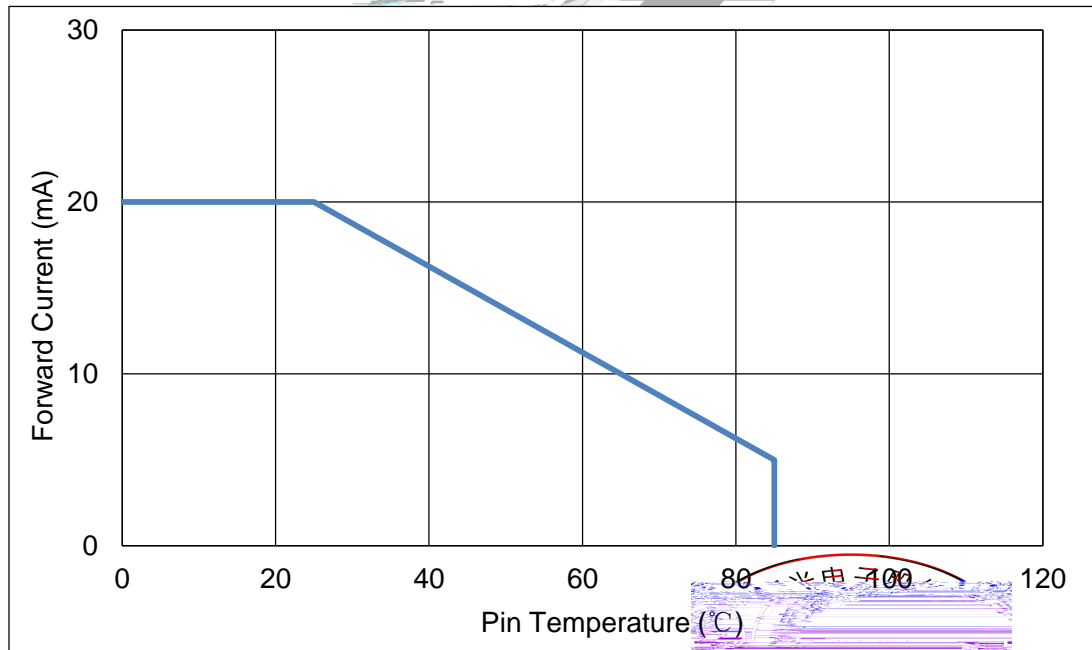


Fig 1-9 Pin Temperature Vs Forward Current

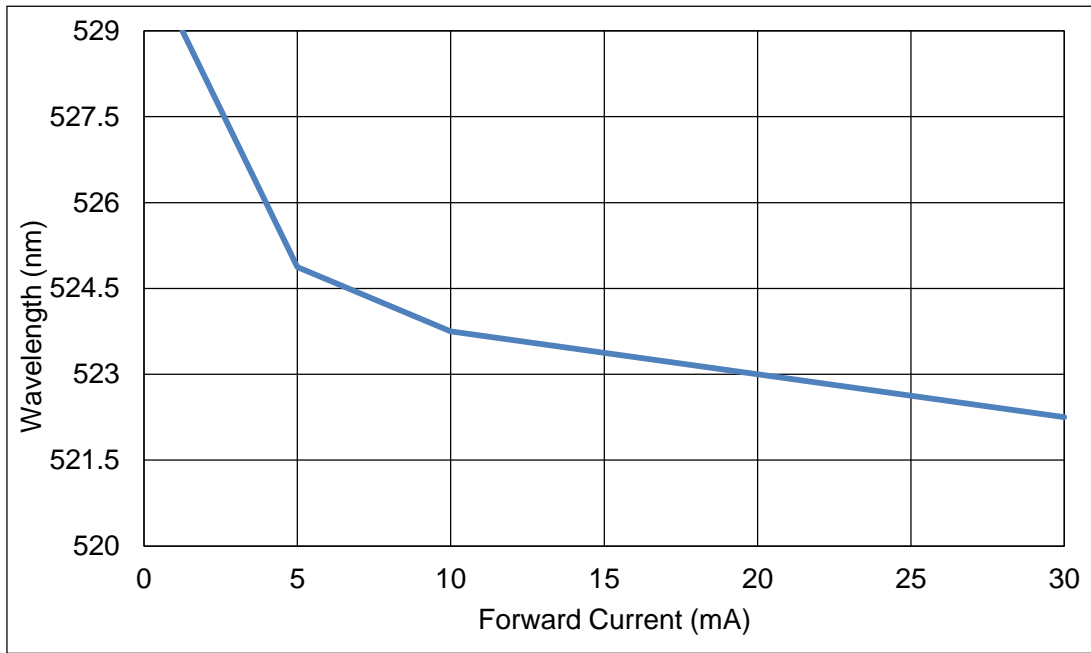


Fig 1-10 Forward Current Vs. Dominate Wavelength (Ta=25°C)

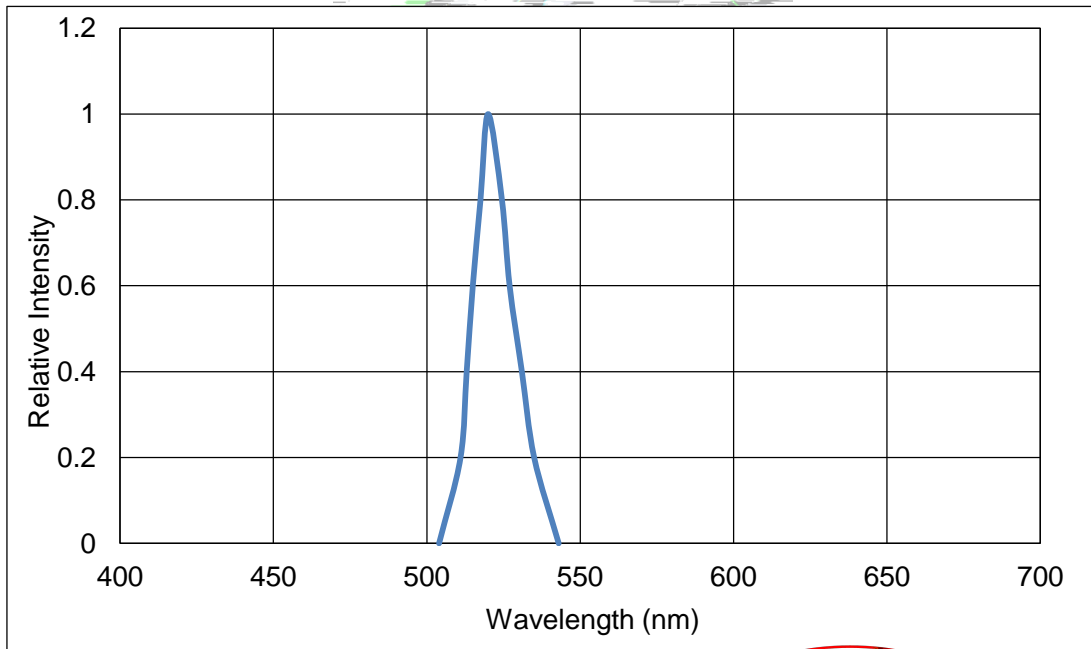
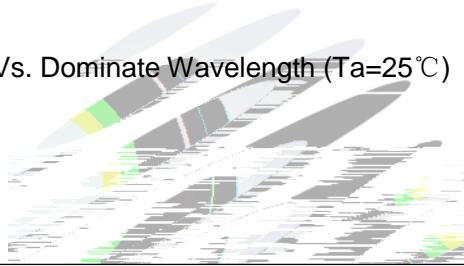
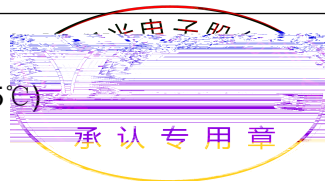


Fig 1-11 Relative Intensity Vs. Wavelength (Ta=25°C)



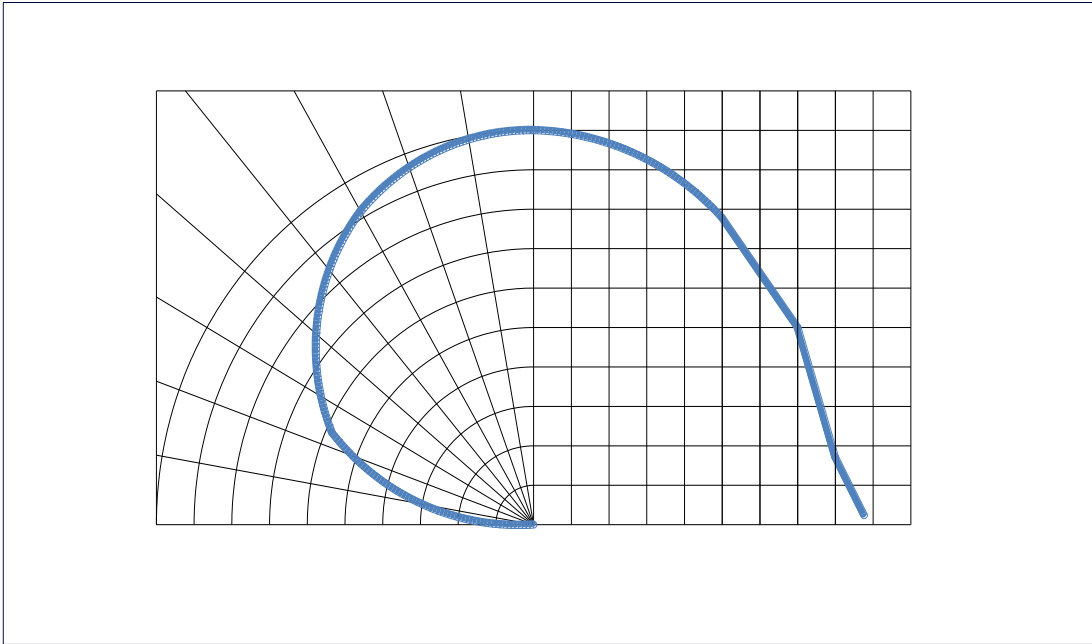
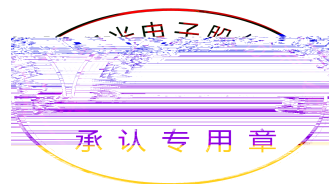
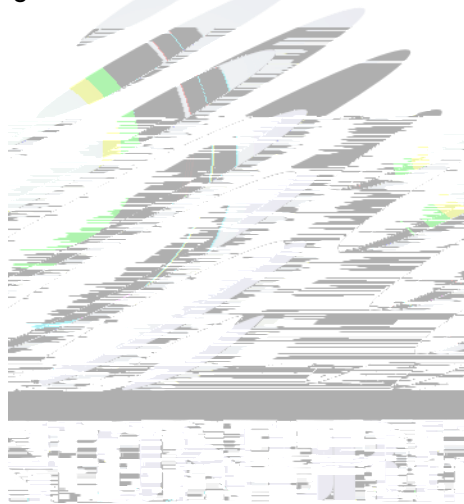


Fig 1-12 Diagram characteristics of radiation



2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel. 4000pcs

2.1.1 Carrier Tape Dimension

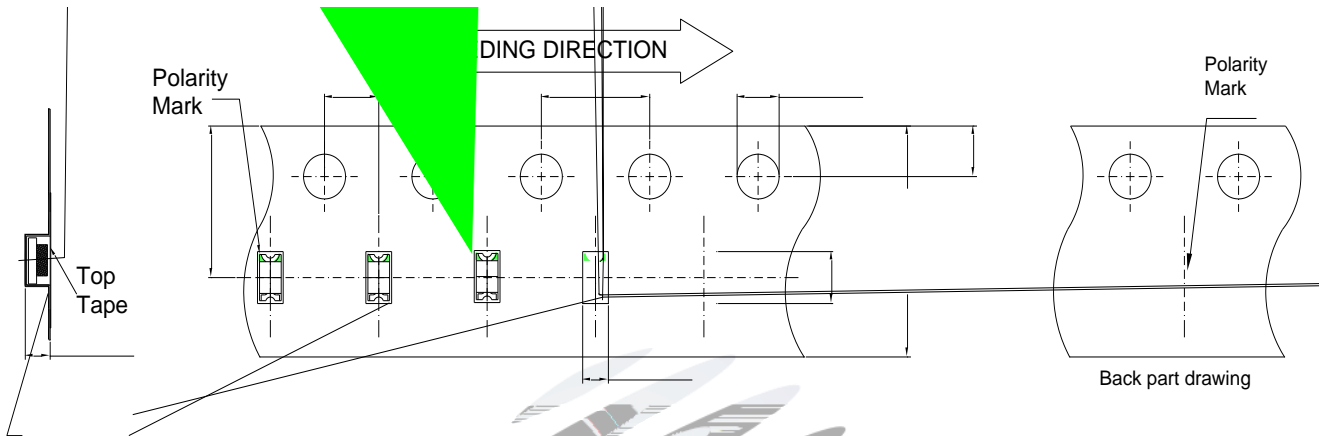


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

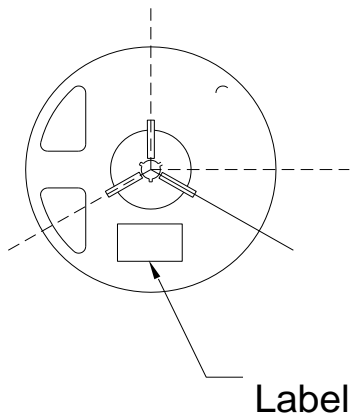


Fig.2-2 Reel Dimension

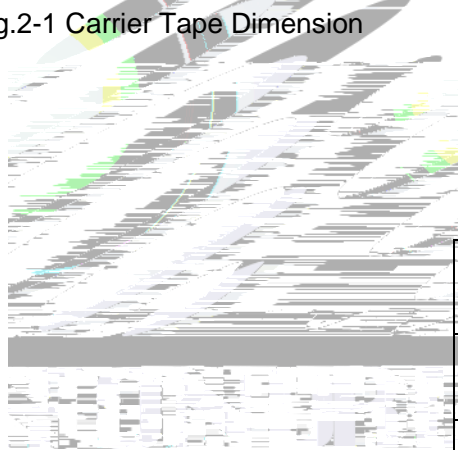


Table 2-1 Dimension

| | |
|---|------------|
| A | 8.0 0.1mm |
| B | 178 1mm |
| C | 60 1mm |
| D | 13.0 0.5mm |

Notes

The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm

2.1.3 Label Form Specification

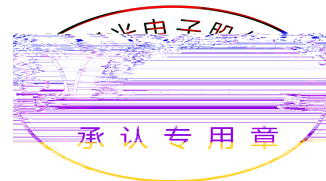


Table 2-2 Parameter

| | |
|----------------|------------------|
| PART NO. | Part Number |
| SPEC NO. | Spec Number |
| LOT NO. | Lot Number |
| BIN CODE | Bin Code |
| | Luminous flux |
| XY | Chromaticity Bin |
| V _F | Forward Voltage |
| WLD | Wavelength |
| QTY | Packing Quantity |
| DATE | Made Date |

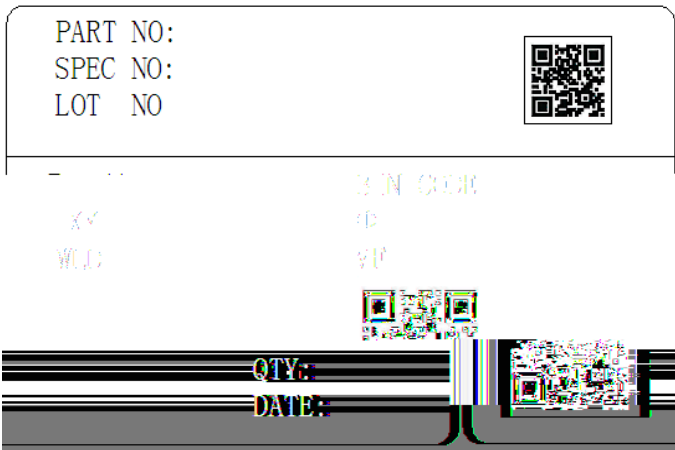


Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing

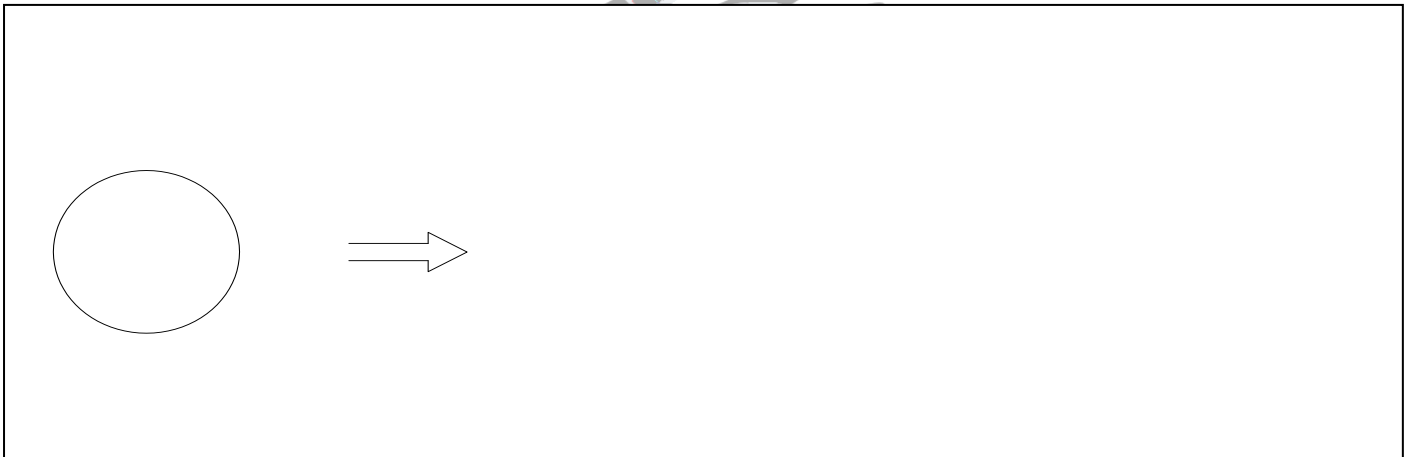
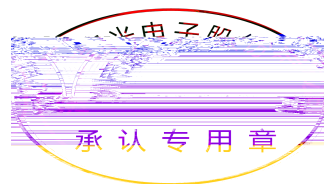


Fig.2-4 Moisture Resistant Packing



2.3 Cardboard Box

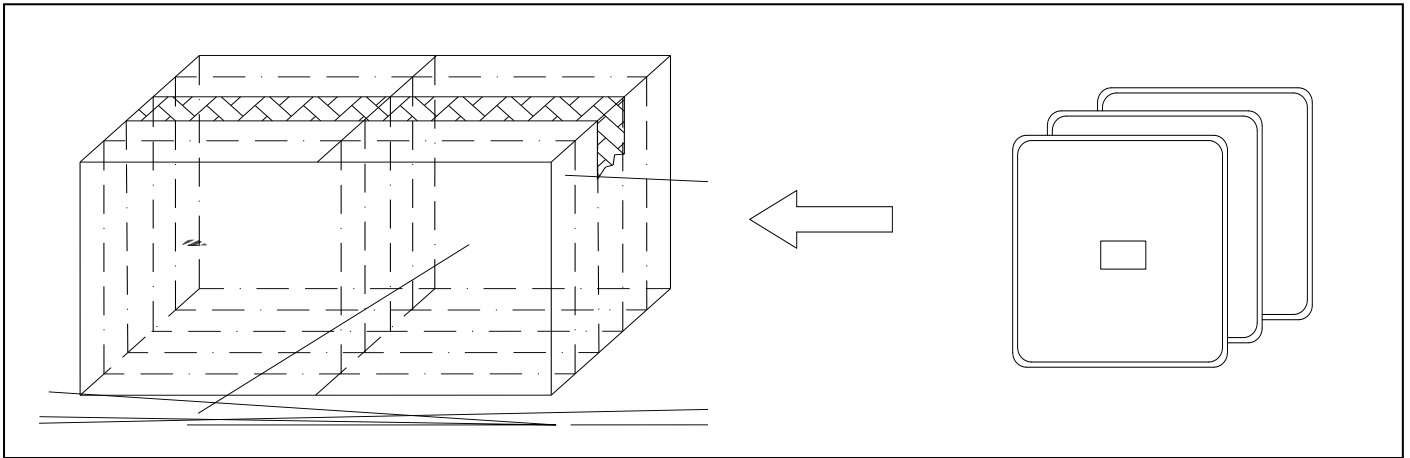
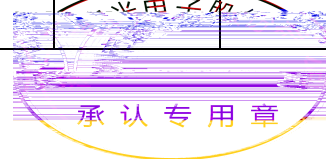


Fig.2-5 Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

| Test Items | Ref.Standard | Test Condition | Time | Quantity | Ac/Re / |
|--------------------------|--------------|---|------------|----------|---------|
| Reflow | JESD22-B106 | Temp:260 max T=10 sec | 2 times | 22Pcs. | 0/1 |
| Temperature Cycle | JESD22-A104 | 100 30 min 5 min -40 30 min | 50 cycles | 22Pcs. | 0/1 |
| Thermal Shock | JESD22-A106 | -40 15min 100 15min | 150 cycles | 22Pcs. | 0/1 |
| High Temperature Storage | JESD22-A103 | Temp:100 | 500 hrs. | 22Pcs. | 0/1 |
| Low Temperature Storage | JESD22-A119 | Temp:-40 | 500 hrs. | 22Pcs. | 0/1 |
| Life Test | JESD22-A108 | T _a =25 I _f =5mA | 500 hrs. | 22Pcs. | 0/1 |



2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

| Test Items | Symbol | Test Condition | Criteria For Judgement | |
|-----------------|--------|----------------|------------------------|-------------|
| | | | 最小 | Max. |
| Forward Voltage | V_F | $I_F=5mA$ | - | U.S.L*)x1.1 |
| Reverse Current | I_R | $V_R= 5V$ | - | U.S.L*)x2.0 |
| Luminous Flux | | $I_F=5mA$ | L.S.L*)x0.7 | - |

Notes

1.U.S.L: Upper standard level

L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a s357.8 0.008645P27e/6(oand)9t

3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

Fig.3-1 SMT Reflow Soldering Instructions SMT

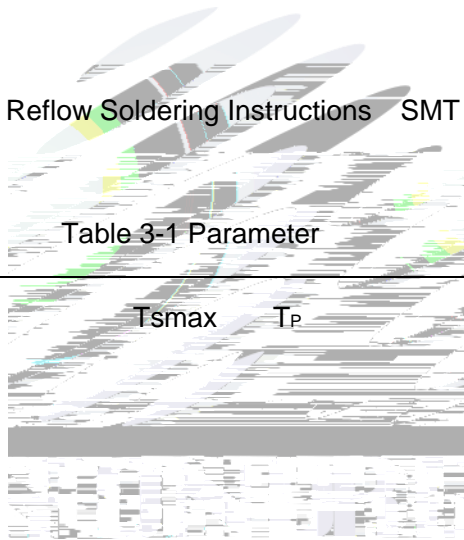


Table 3-1 Parameter

Average temperature rise speed

T_{max} T_p

3 °C/ Max 3 °C/ s

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged.

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

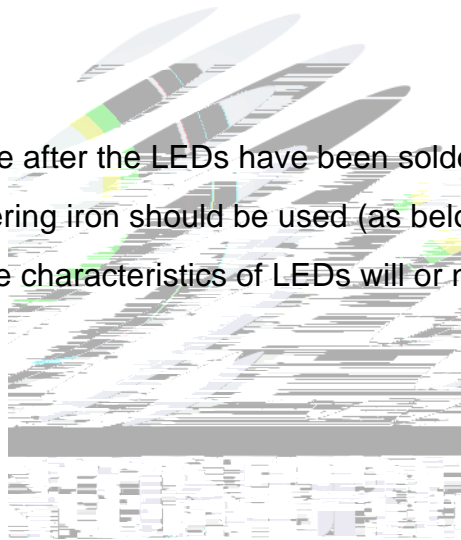
(1) When do soldering by hand, keep the temperature of iron below less 300°C less than 3 seconds.

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

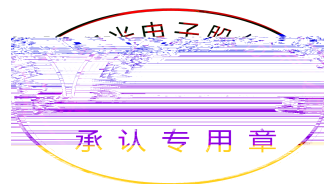
LED



3.1.3 Cautions

(1) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.



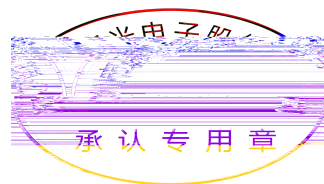
4. Handling Precautions

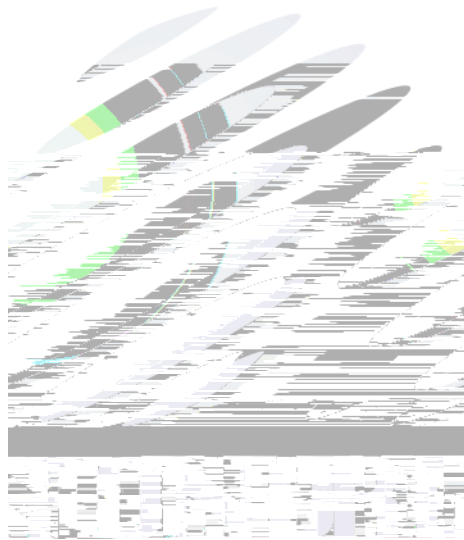
4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

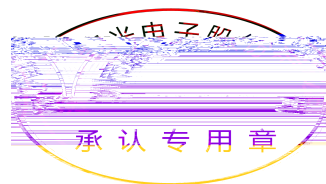
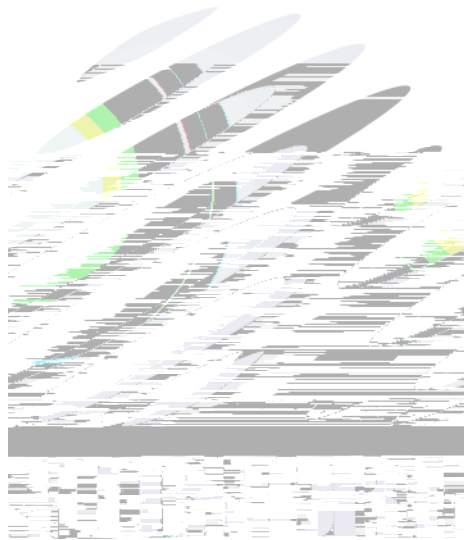
(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.



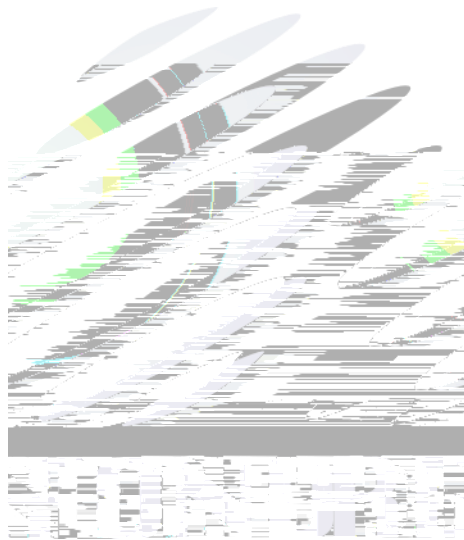


(8) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

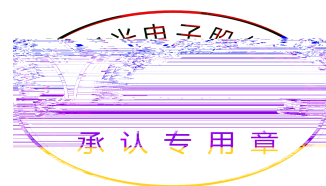
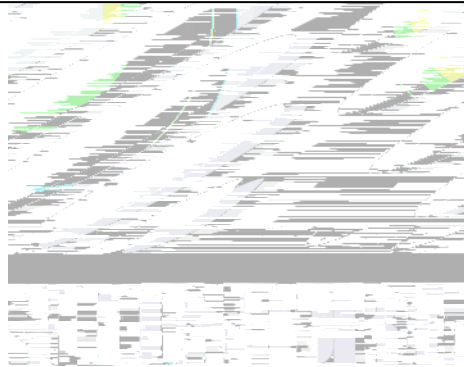
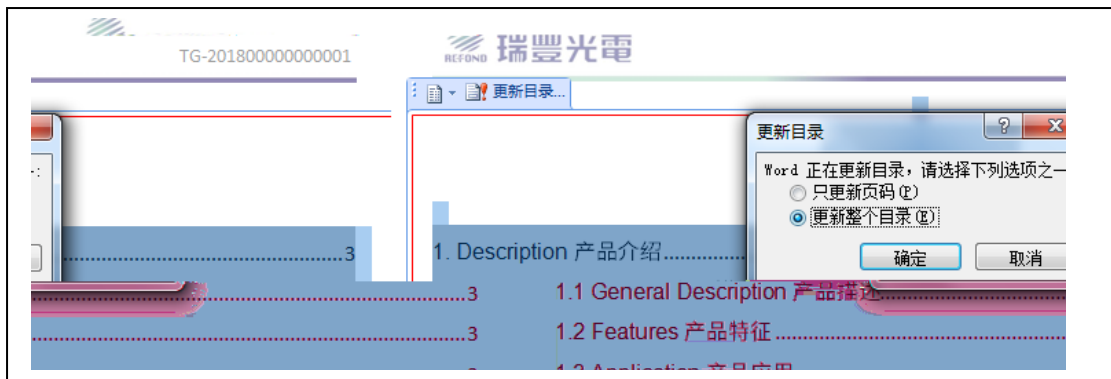
(9) Other points for attention, please refer to our relevant information.



| Date | Revisor | Version | Verifier | Remarks |
|------------|---------|---------|----------|---------|
| 2020.08.31 | | E/0 | | |
| 2021.5.10 | | E/1 | | |
| | | | | |
| | | | | |



| | | | | |
|--|--|--|--|--|
| | | | | |
|--|--|--|--|--|





Declare

This specification is written both in English and in Chinese and the latter is formal.

